TE Internal #: 2321882-3

PCB Mount Header, Horizontal, Wire-to-Board, 3 Position, 2.54 mm

[.1 in] Centerline, Fully Shrouded, Tin, Through Hole - Solder,

Signal, Natural

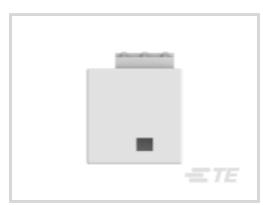
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Connectors > PCB Connectors > PCB Headers & Receptacles











PCB Connector Assembly Type: PCB Mount Header

PCB Mount Orientation: Horizontal Connector System: Wire-to-Board

Number of Positions: 3

Number of Rows: 1

Features

Packaging Features

Packaging Quantity	600
Packaging Method	Carton

Body Features

Connector & Keying Code	A
Primary Product Color	Natural

Operation/Application

Solder Process	Reflow Solder
Shielded	No
Circuit Application	Signal

Contact Features

Mating Tab Thickness	.63 mm[.025 in]
Contact Size	.63mm
Mating Tab Width	.63 mm[.025 in]
Contact Mating Area Plating Material	Tin



Contact Type	Tab
Contact Current Rating (Max)	7.5 A
Product Type Features	
Mixed & Hybrid Header	No
Connector Shape	Rectangular
PCB Connector Assembly Type	PCB Mount Header
Connector System	Wire-to-Board
Header Type	Fully Shrouded
Sealable	No
Connector & Contact Terminates To	Printed Circuit Board
Configuration Features	
PCB Mount Orientation	Horizontal
Number of Positions	3
Number of Rows	1
Termination Features	
Termination Method to PCB	Through Hole - Solder
Mechanical Attachment	
Connector Mounting Type	Board Mount
Mating Alignment	With
Housing Features	
Centerline (Pitch)	2.54 mm[.1 in]
Usage Conditions	
Operating Temperature Range	-40 – 120 °C[-40 – 248 °F]
Other	
EU RoHS Compliance	Compliant
EU ELV Compliance	Compliant

Product Compliance

For compliance documentation, visit the product page on TE.com>

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold



EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2024 (241) Candidate List Declared Against: JUNE 2024 (241) Does not contain REACH SVHC
Halogen Content	Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free
Solder Process Capability	Not reviewed for solder process capability

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

Compatible Parts



Customers Also Bought



















Documents

Product Drawings

3POS,TAB0.63X0.63,HDR ASSY,90DEG

English

CAD Files

3D PDF

3D

Customer View Model

ENG_CVM_CVM_2321882-3_B.2d_dxf.zip

English

Customer View Model

ENG_CVM_CVM_2321882-3_B.3d_igs.zip

English

Customer View Model

ENG_CVM_CVM_2321882-3_B.3d_stp.zip

English

By downloading the CAD file I accept and agree to the **Terms and Conditions** of use.

Product Specifications

Application Specification

German